

1 **ABSTRACT OF THE DISCLOSURE**

2 A packaging method for preparing thin integrated circuits comprises:
3 forming a circuit layer with multiple sections on a substrate; attaching
4 multiple electronic elements to the circuit layer between two sections of the
5 circuit layer; applying an encapsulant layer to protect the electronic elements;
6 and removing the substrate to expose the circuit layer. By removing the
7 substrate, the exposed circuit can be connected to another circuit board and
8 the integrated circuit is much thinner.